

FIG. 2.

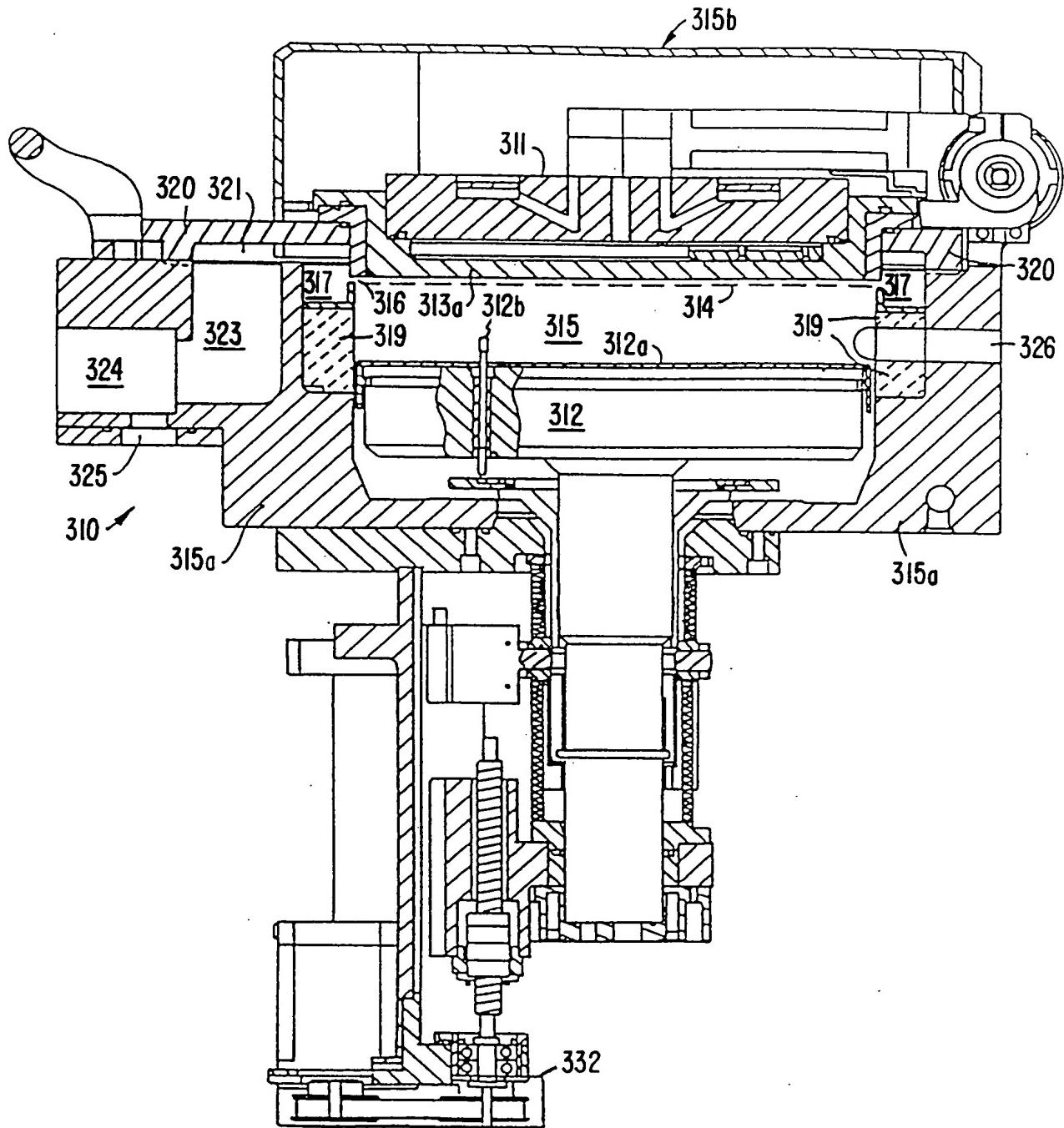


FIG. 3A.



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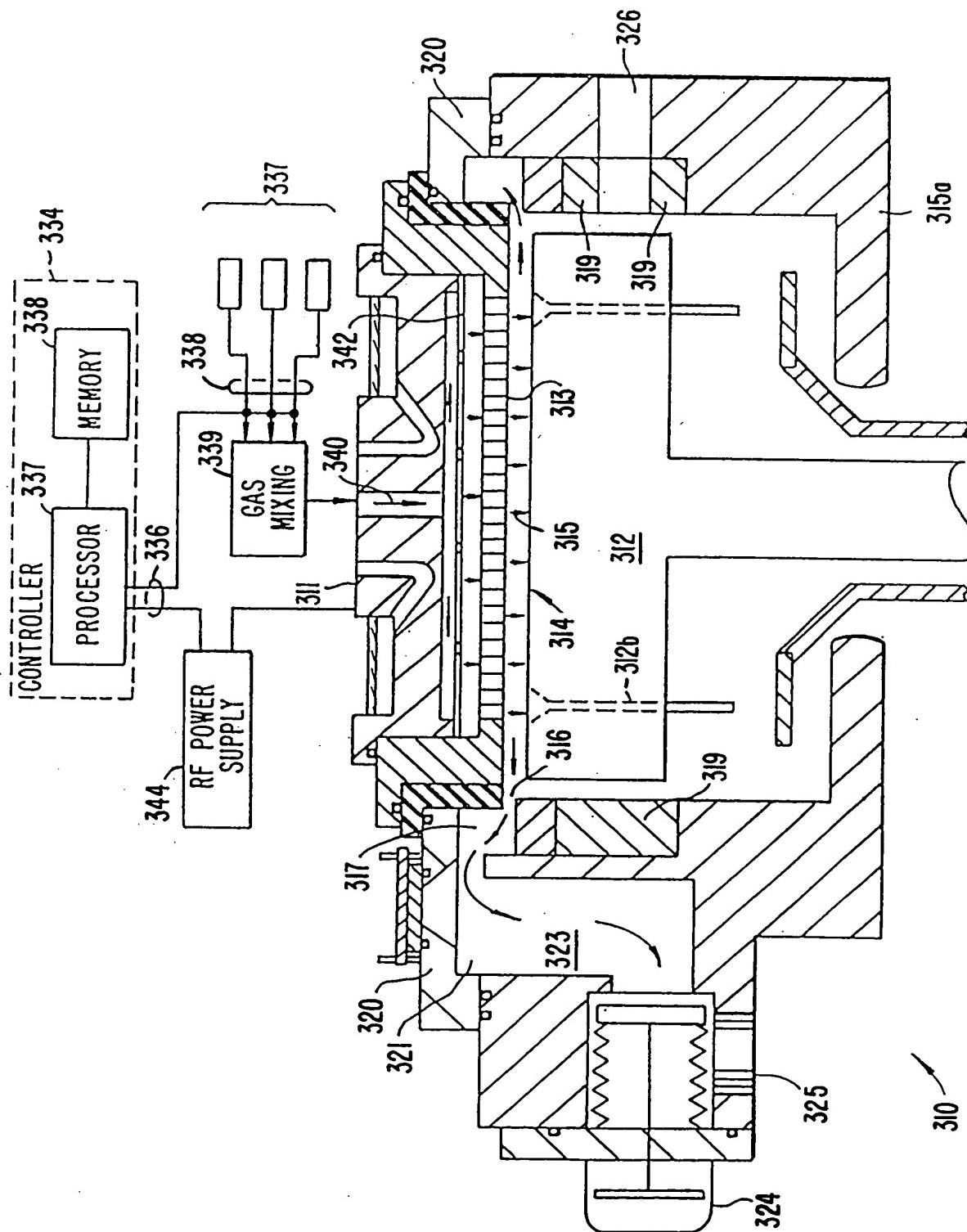
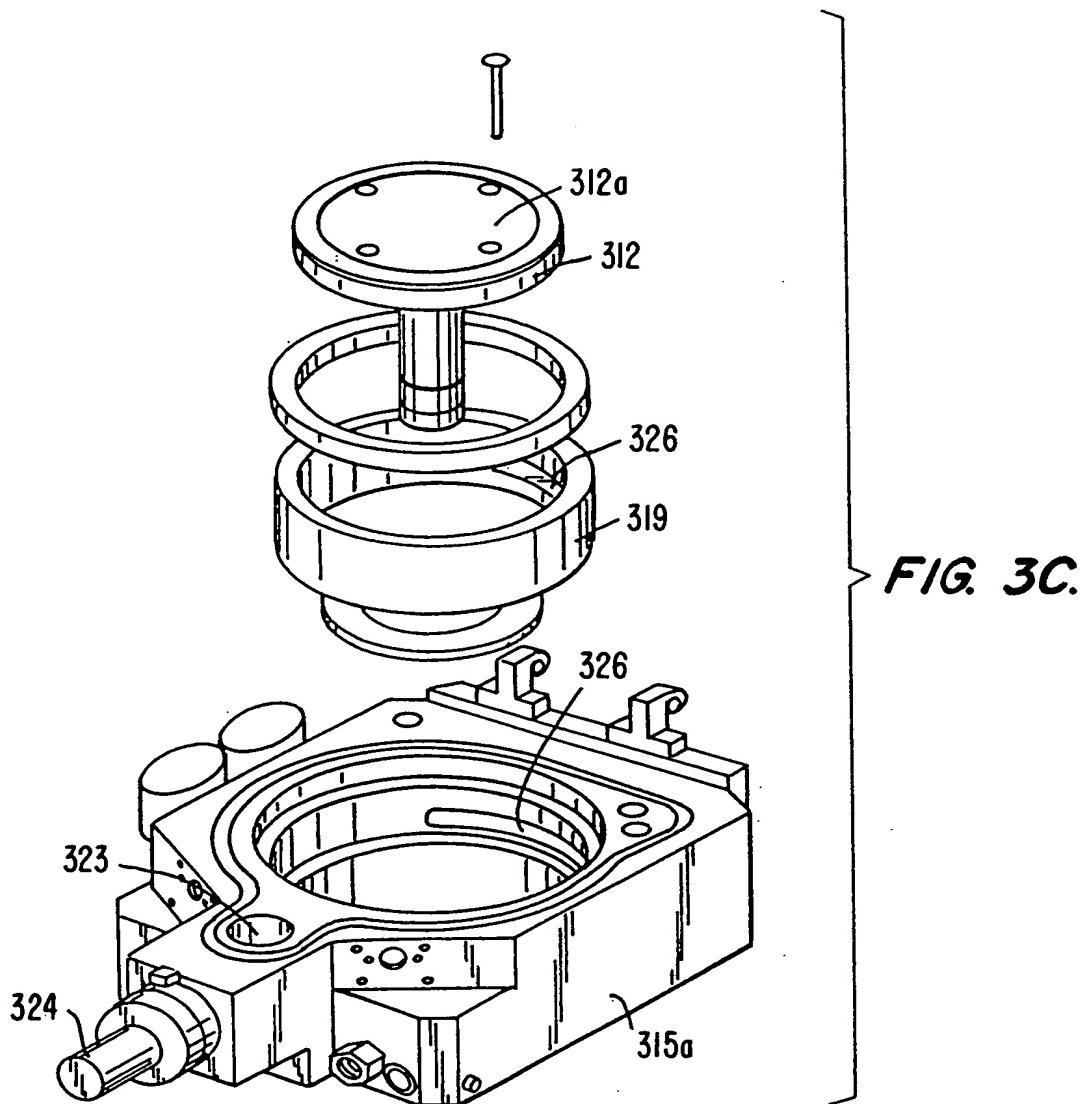


FIG. 3B.



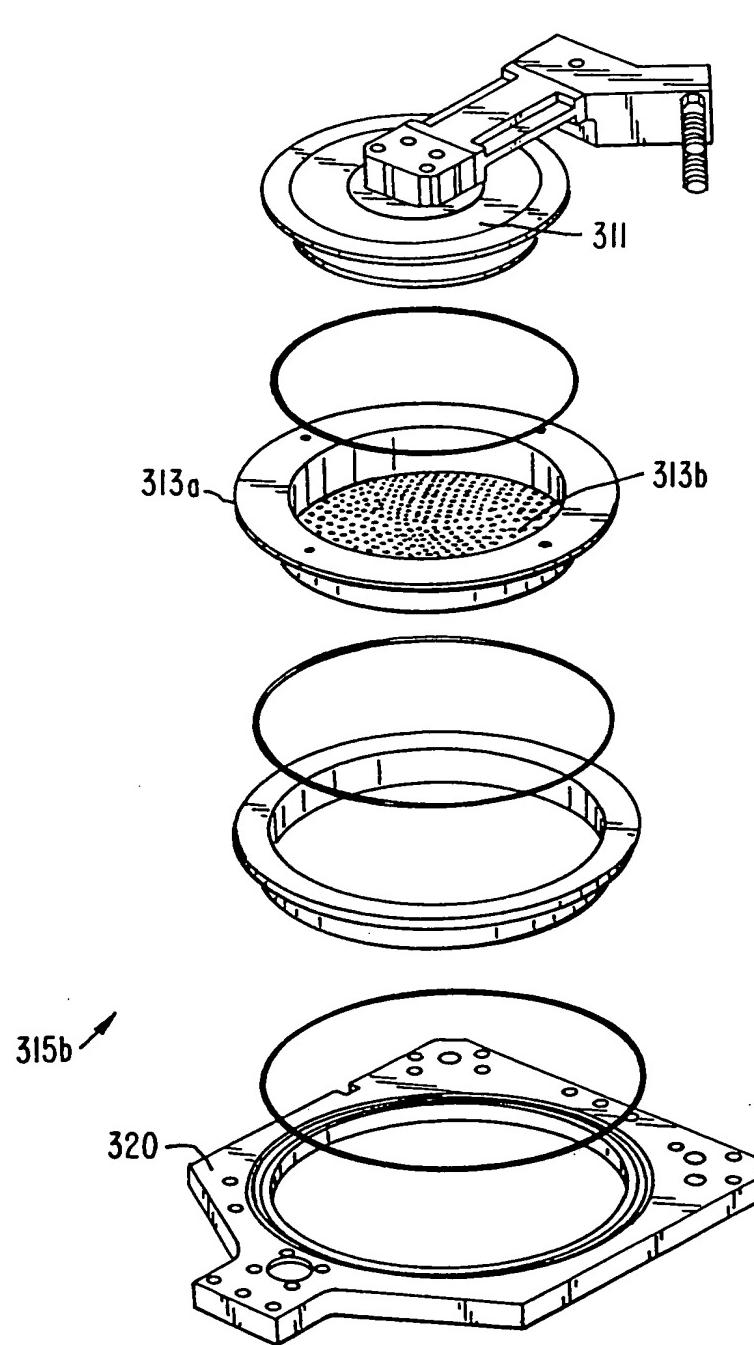


FIG. 3D.

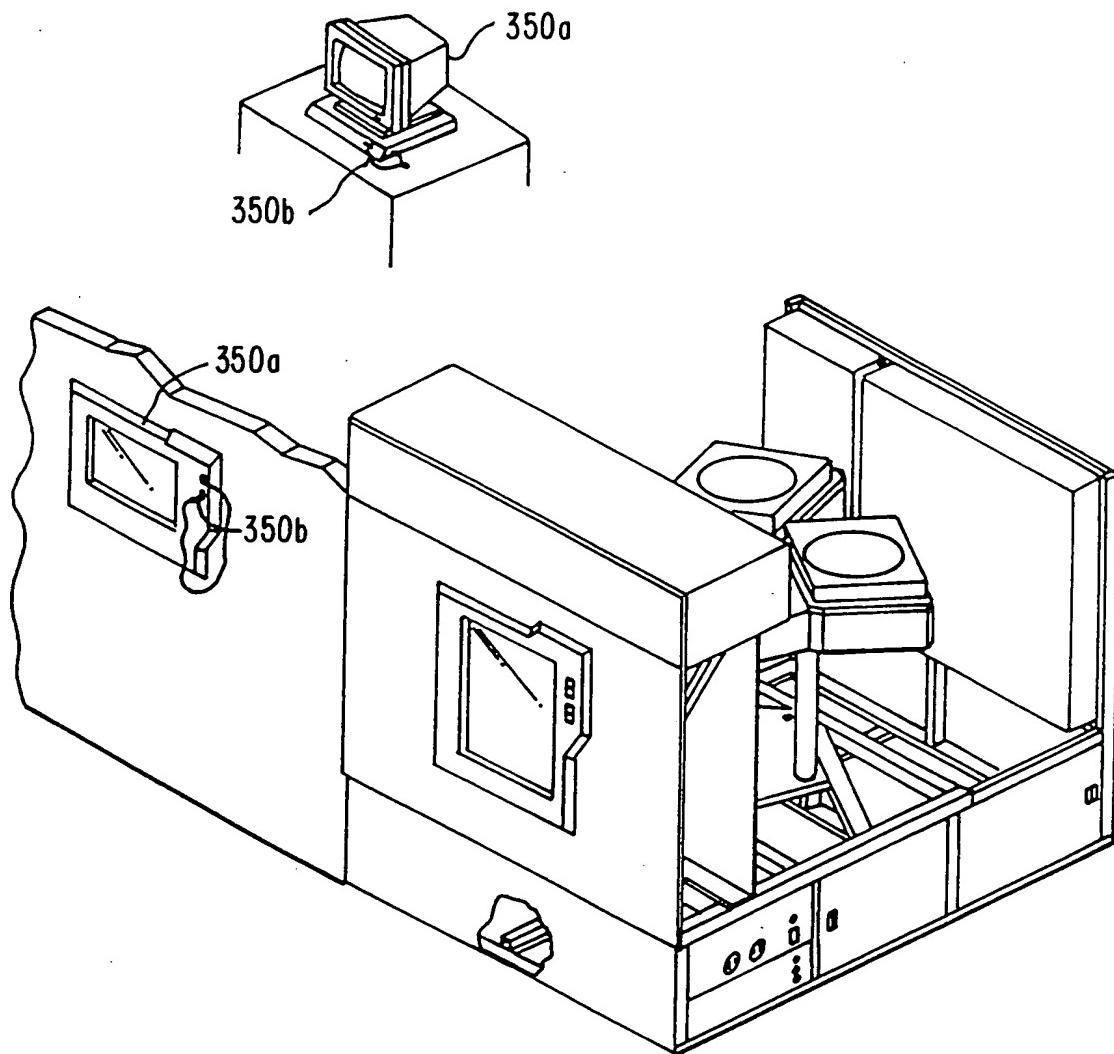


FIG. 3E.

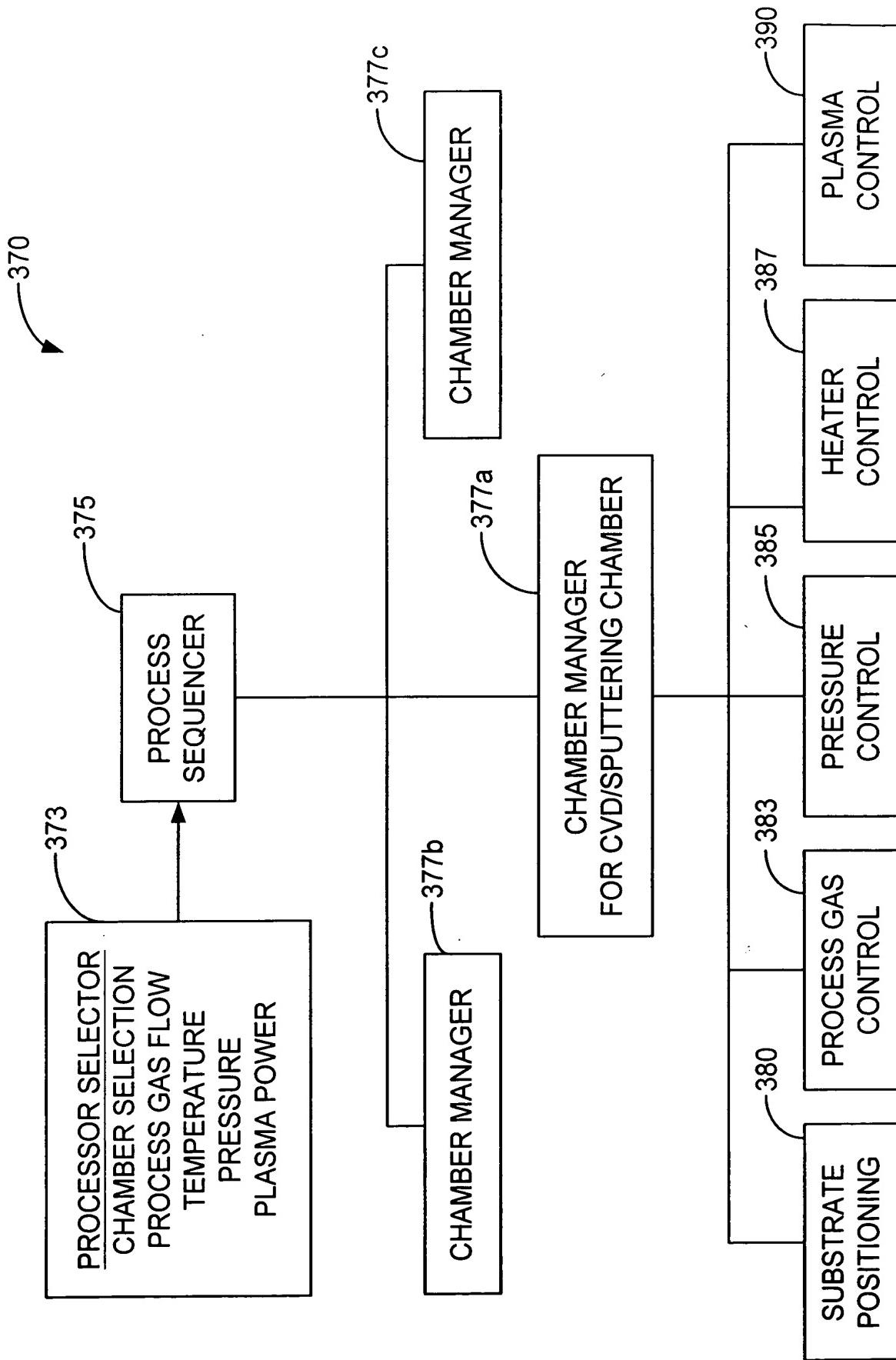


FIG. 4.



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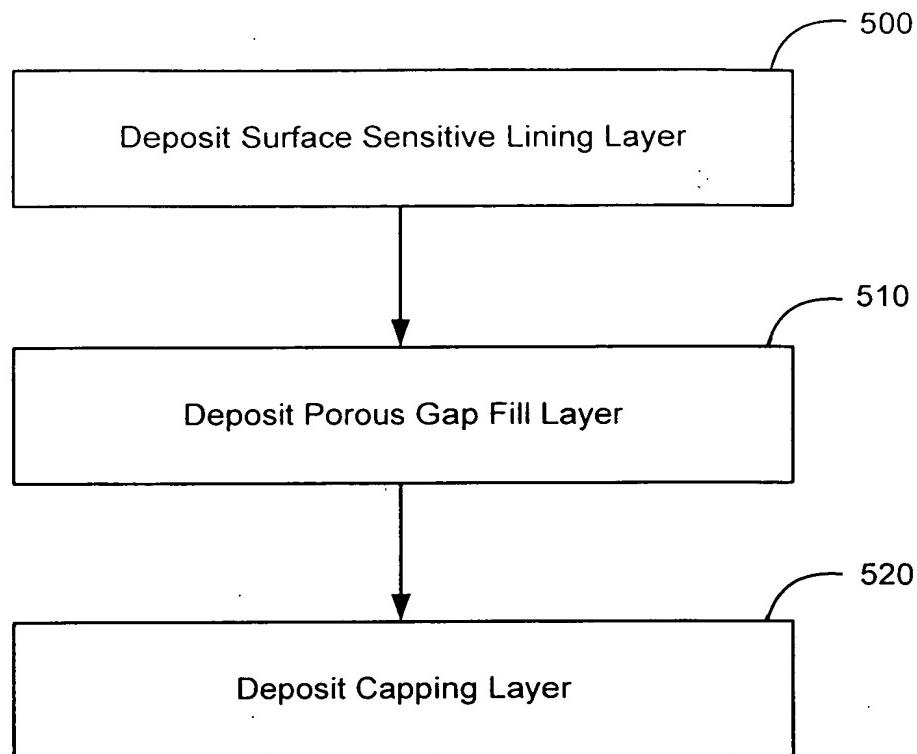


Fig. 5